

PRODUCT CHANGE NOTICE

PCN Form (D4-E000-73)

PCN#18-043

NOTIFICATION DATE: April 23, 2018

MODEL(S) AFFECTED:

JCIQ-156D-1+	JCIQ-336D-1	JCIR-1015H-1+	JCPS-6-10-1+
JCIQ-156M-1+	JCIQ-336M-1	JCIR-15-2A+	JCPS-6-1450-1
JCIQ-176D	JCIQ-400D-1+	JCIR-152H+	JCPS-6-3
JCIQ-176D+	JCIQ-400M-2+	JCIR-25+	JCPS-6-3-3
JCIQ-176M	JCIQ-70D-12	JCIR-2630-1	JCPS-8-10+
JCIQ-176M+	JCIQ-88M	JCIR-4MH	JCPS-8-850
JCIQ-176MH-1	JCIQ-88M+	JCIR-4MH+	JCPS-8-850+
JCIQ-1880D	JCIQ-88M-4+	JCIR-4MH-1N+	JCPS-8-850-75+

EXTENT OF CHANGE:

Change of solder used in cover attachment process

EFFECT OF CHANGE:

Enhanced cover attachment to withstand customer higher temperature assembly process.

From:	To:
SnAgCu solder plus Epoxy dots	High temperature solder plus Epoxy dots

REASON FOR CHANGE:

Increased use of higher reflow temperatures by customers requires a more robust cover attachment method. High temperature solder will not be affected by customer reflow. Epoxy dots at corners retained to add mechanical strength.

EFFECTIVE DATE OF CHANGE:

Immediate

ATTACHMENTS:

n/a

QUESTIONS?

[PLEASE CONTACT US.](#)